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Table 4-4

	Example			
	17	18	19	20
Component (X)	XA-4	XA-4	XA-4	XA-4
Component (H)	H-1	H-2	H-3	H-4
Development	○	○	○	○
Soldering-heat resistance	○	○	○	○
Flexibility	○	○	○	○
Heat-deterioration resistance	○	○	○	○
Nonelectrolytic gold-plating resistance	○	○	○	○

Table 4-5

	Comparative Example			
	2	3	4	5
Component (X)	XX-1	XX-1	XX-1	XX-1
Component (H)	H-1	H-2	H-3	H-4
Development	○	○	○	○
Soldering-heat resistance	○	○	○	○
Flexibility	△	△	×	×
Heat-deterioration resistance	△	△	×	×
Nonelectrolytic gold-plating resistance	○	○	○	○

The results of Example 5-20 and Comparative Example 2-5

reveal that the resin compositions of the present invention allow a good alkali development and can provide a cured membrane that is excellent in soldering-heat resistance, flexibility, heat-deterioration resistance, and nonelectrolytic gold-plating.

#### Example 21 and Comparative Example 6

(XA-5) and (XX-2) were each applied to a polyethylene terephthalate films having a thickness of  $25\mu\text{m}$  uniformly and dried to remove solvent. The dried photosensitive layers had a thickness of  $50\mu\text{m}$ . Then, each of the photosensitive layers was covered with a polyethylene film for the protective film to prepare a photosensitive laminated product.

A substrate for FPC (Trade name:F30VC125RC11, made by Nikkan Kogyo KK) obtained by laminating a  $35\mu\text{m}$  thick copper foil on a polyimide base material was polished with a whetting brush, washed with water, and dried. The said photosensitive film was laminated on the above substrate ( $23^{\circ}\text{C}$ ) by a vacuum laminator.

The sample thus obtained was exposed to light at  $200\text{mJ}/\text{cm}^2$  by using the Stoffer's step tablet of 21 steps and a straight line of negative film having a line/space of  $150\mu\text{m}/150\mu\text{m}$ , and was left at a room temperature for 30 minutes. The sample was